

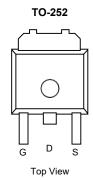
## EMB09P03A-VB Datasheet P-Channel 30 V (D-S) MOSFET

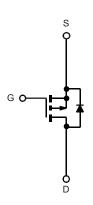
PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>			
- 30	0.009 at V <sub>GS</sub> = - 10 V	-60			
	0.011 at V <sub>GS</sub> = - 4.5 V	-58			

#### **FEATURES**

• Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Limit	Unit				
Gate-Source Voltage		V <sub>GS</sub>	± 20	V			
Continuous Drain Current (T <sub>.1</sub> = 175 °C)	T <sub>C</sub> = 25 °C	I-	- 70ª				
Continuous Diain Current (1j = 173 C)	T <sub>C</sub> = 125 °C	I <sub>D</sub>	- 58	A			
Pulsed Drain Current	I <sub>DM</sub>	- 240					
Avalanche Current	I <sub>AR</sub>	- 60					
Repetitive Avalanche Energy <sup>b</sup>	L = 0.1 mH	E <sub>AR</sub>	180	mJ			
Power Dissipation	T <sub>C</sub> = 25 °C	В	87 <sup>d</sup>	W			
Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	78	l vv			
Operating Junction and Storage Temperatu	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C				

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount	- R <sub>thJA</sub>	60			
Junction-to-Ambient	Free Air		68.5	°C/W		
Junction-to-Case		R <sub>thJC</sub>	1.0			

#### Notes:

- a. Package limited.
- b. Duty cycle  $\leq$  1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply.



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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA	- 30			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	- 1		- 3	V	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V			± 100	nA	
		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			- 50	μА	
		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			- 250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.009			
Drain-Source On-State Resistance <sup>a</sup>	D	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 125 °C		0.012		Ω	
Diain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A, T <sub>J</sub> = 175 °C		0.013			
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.011			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 75 A	20			S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			4000		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = - 25 V, f = 1 MHz		1565			
Reversen Transfer Capacitance	C <sub>rss</sub>			715			
Total Gate Charge <sup>c</sup>	Qg			160	240		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 75 A		32		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			30		1	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			25	40		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, R_L = 0.2 \Omega$		225	360	20	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong -75 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		150	240	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>	]		210	340		
Source-Drain Diode Ratings and Cha	racteristicsb	(T <sub>C</sub> = 25 °C)					
Continuous Current	Is				- 70	^	
Pulsed Current	I <sub>SM</sub>				- 240	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = - 75 A, V <sub>GS</sub> = 0 V		- 1.2	- 1.5	V	
Reverse Recovery Time	t <sub>rr</sub>			55	100	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = - 75 A, dI/dt = 100 A/μs		2.5	5	Α	
Reverse Recovery Charge	Q <sub>rr</sub>	1		0.07	0.25	μC	

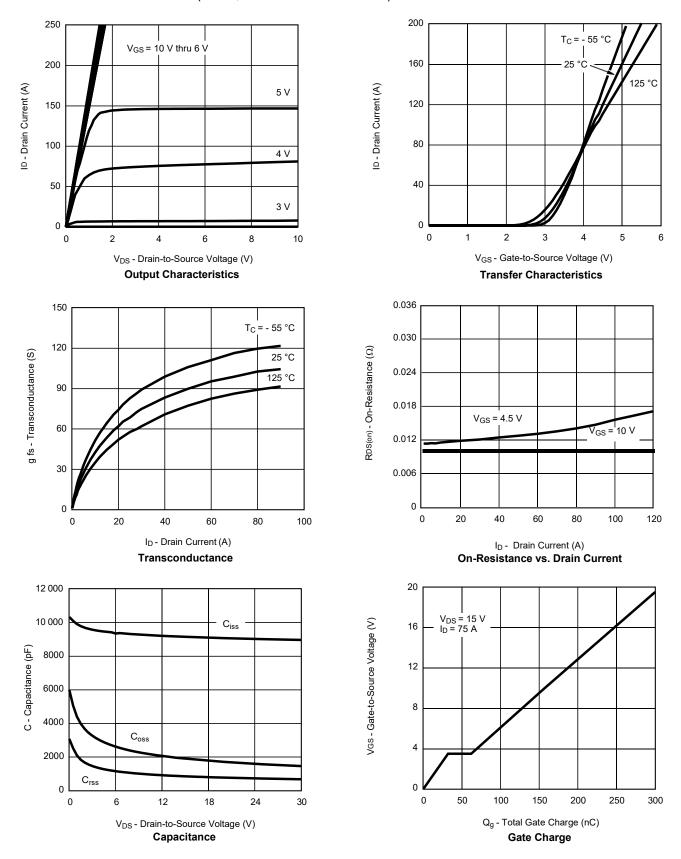
#### Notes:

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

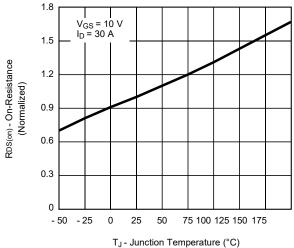


#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

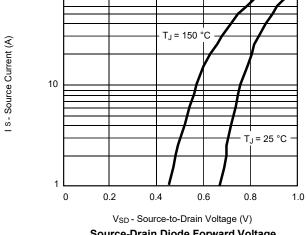




### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

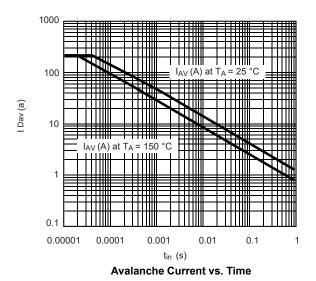


On-Resistance vs. Junction Temperature



100

Source-Drain Diode Forward Voltage

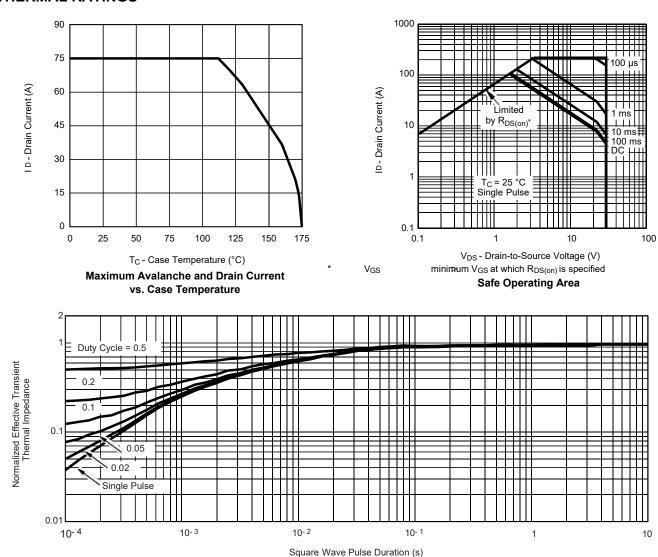


45  $I_D = 250 \mu A$ 40 VDS (V) 35 30 25 - 50 - 25 0 25 50 75 100 125 150 175 T<sub>J</sub> - Junction Temperature (°C)

> **Drain Source Breakdown** vs. Junction Temperature



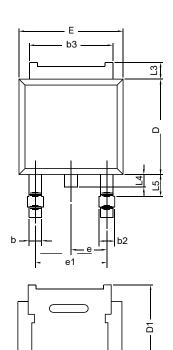
#### **THERMAL RATINGS**

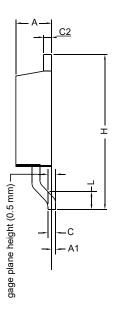


Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-252AA CASE OUTLINE**





	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	BSC	0.180	BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M, 24-Dec-12					

DWG: 5347

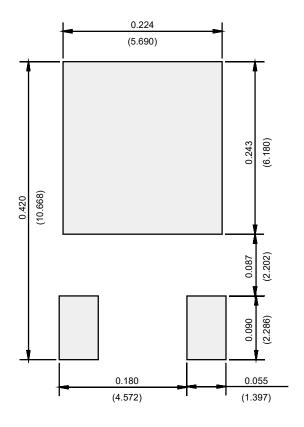
#### Note

• Dimension L3 is for reference only.



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#### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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